

REMARKS

Claims 1, 3-4 and 6-22 were previously pending in the application.

Claims 8-12 are withdrawn from consideration.

Claims 1, 3-4, 6-7 and 13-22 are rejected.

Claims 1, 3-4 and 13-22 are rejected under 35 U.S.C. 102(b).

Claims 1, 3-4, 6-7 and 13-22 are rejected under 35 U.S.C. 103(a).

Claims 1 and 14 are amended.

Claim 20 is cancelled, without prejudice, in favor of amended claim 14.

Claims 13 and 22 are cancelled, without prejudice.

No new matter is added.

Claims 1, 3-4, 6-7, and 14-19, and 21 remain in the case for consideration.

Applicant requests reconsideration and allowance of the claims in light of the following remarks.

Claim Rejections – 35 U.S.C. § 102

Claims 1, 3-4 and 13-22 are rejected under 35 U.S.C. 102(b) as being anticipated by U.S. Patent Application Publication No. 2003/0168725 to Warner, et al (“Warner”).

Claims 1-4 and 13-22 are rejected for the same reason as set forth in the previous Office Action dated April 4, 2005.

Applicants respectfully traverse the rejections.

Claim 1 is amended to recite, “the bottom surface of the first molding resin contacting the top surface of said first substrate portion and covering the top surface of said first integrated circuit chip.” Support for the limitation can be found in FIG. 2 and the accompanying text.

In the previous response to office action, applicants respectfully submitted that some features of U.S. Patent Application Publication No. 2003/0168725, e.g., FIG. 4, relied on by the Examiner to reject the claimed invention are *not* shown or disclosed in either of the U.S. Patent No. 6,121,676 (“‘676 patent”) or U.S. Patent. No. 6,255,688 (“‘688 patent”), i.e., new matter to these patents. For example, nowhere does ‘676 patent or ‘688 patent teach or disclose, among other limitations, “the bottom surface of the first molding resin contacting the top surface of said first substrate portion and covering the top surface of said first integrated circuit chip.” See the molding resin 933b shown in FIG. 28 of ‘688 patent. In particular, in ‘688 patent, the bottom surface of the molding resin 933b covering the top

surface of the chip 926b does not contacts the top surface of the first substrate portion and separate molding resins are spaced apart from each other with the chips 926b and an adhesive 902b disposed therbetween.

Also, claim 10 is amended to recite, "a molding resin having a bottom surface that contacts the top surface of the first integrated circuit and the top surface of the first substrate portion, the bottom of said third substrate portion is positioned on top of said molding resin," similar to the above discussed limitations of claim 1.

Accordingly, the above dates cannot be used to precede the dates of supporting documents presented by applicants as the features of Warner are not supported by the '676 patent or '688 patent. Thus, Warner is not a prior art to the present application and, therefore, claims 1-4, 6-7 and 14-21 are patentable under 35 U.S.C. 102(e) over Warren.

Claim Rejections – 35 U.S.C. § 103

Claims 6 and 7 are rejected under 35 U.S.C. 103(a) as being unpatentable over U.S. Patent Application Publication No. 2003/0168725 to Warner, et al. in view of U.S. Patent No. 6,576,493 to Lin, et al.

Claims 6 and 7 are rejected for the same reason as set forth in the previous Office Action dated April 4, 2005.

Applicants respectfully traverse the rejections.


As discussed above, Warner is not a prior art to the present application. Therefore, the rejection under Section 103(a) is moot.

In conclusion

For the foregoing reasons, reconsideration and allowance of claims 1, 3-4, 6-7, and 14-19, and 21 of the application as amended is solicited. The Examiner is encouraged to telephone the undersigned at (503) 222-3613 if it appears that an interview would be helpful in advancing the case.

Respectfully submitted,

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is being transmitted to the U.S. Patent and
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(571) 273-8300 on January 17, 2006.



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